

AMENDMENTS TO THE SPECIFICATION

(1) Please amend page 1, lines 27-29 of the Specification, as originally filed, as follows:

~~The present invention provides method and apparatus as defined in independent claims 1, 2 and 4.
Preferred features of the invention are set out in the dependent claims.~~

(2) Please amend page 3, lines 10-17 of the Specification, as originally filed, as follows:

An array 1 of connected components 2 may be (see FIG. 1) made by deposition on a sacrificial substrate [[5]] (see FIG. 2). First a metal seed layer of, for example, gold is vacuum deposited on a sacrificial substrate of, for example, silicon. A pattern matching the desired shape of the interconnected array of components (see FIG. 1) is defined in the seed layer by photolithography and/or chemical etching. A conductive material such as gold is then deposited in the defined pattern in the seed layer by electroplating through a photoresist mask. This is a known process.

(3) Please amend page 3, lines 22-31 of the Specification, as originally filed, as follows:

In the embodiment of the invention illustrated in FIG. 3, the element 2' to be separated from the array 1 is positioned on an insulating area 7 underneath an electrically conductive pick-up tool 8. The pick-up tool 8 is brought into contact with and grips the selected element 2. An electrical current is then passed through the pick-up tool 8 and element 2' to the element holder or framework by way of tabs 3 [[4]] holding the element in the array. The current heats up the tabs 3 thereby causing them to melt and free the element 2'. The pick-up tool 8 then lifts the separated element 2'

from the array 1. The pick-up tool 8 may then place the element 2' in an element store or directly on a structure or component of which the element is to form a part.